



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS282Z E3230	Issued	14. May 2021
MA#	MA003062134		
Package	PG-TO220-7-12	Weight*	2125.02 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	13.370	0.63	0.63	6292	6292
chip_2	inorganic material	silicon	7440-21-3	0.454	0.02	0.02	214	214
leadframe	inorganic material	phosphorus	7723-14-0	0.272	0.01		128	
	non noble metal	iron	7439-89-6	0.908	0.04		427	
	non noble metal	copper	7440-50-8	906.793	42.66	42.71	426721	427276
wire	non noble metal	aluminium	7429-90-5	5.419	0.26	0.26	2550	2550
encapsulation	inorganic material	zincoxide	1314-13-2	5.827	0.27		2742	
	miscellaneous	miscellaneous	-	23.307	1.10		10968	
	plastics	epoxy resin	-	87.400	4.11		41129	
	inorganic material	silicondioxide	60676-86-0	466.134	21.94	27.42	219355	274194
leadfinish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10826	10826
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	101	102
solder	non noble metal	tin	7440-31-5	0.164	0.01		77	
	noble metal	silver	7440-22-4	0.204	0.01		96	
	non noble metal	lead	7439-92-1	7.809	0.37	0.39	3675	3848
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	74	74
heatspreader	inorganic material	phosphorus	7723-14-0	0.175	0.01		82	
	non noble metal	iron	7439-89-6	0.584	0.03		275	
	non noble metal	copper	7440-50-8	582.824	27.43	27.47	274267	274624
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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